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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Not For New Designs
Core Processor	M16C/60
Core Size	16-Bit
Speed	20MHz
Connectivity	I <sup>2</sup> C, IEBus, UART/USART
Peripherals	DMA, WDT
Number of I/O	85
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	20K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/m3062lfqgpp-u7c">https://www.e-xfl.com/product-detail/renesas-electronics-america/m3062lfqgpp-u7c</a>

**Table 1.2 Performance Outline of M16C/62P Group (M16C/62P, M16C/62PT)(100-pin version)**

	Item	Performance	
		M16C/62P	M16C/62PT <sup>(4)</sup>
CPU	Number of Basic Instructions	91 instructions	
	Minimum Instruction Execution Time	41.7ns(f(BCLK)=24MHz, VCC1=3.3 to 5.5V) 100ns(f(BCLK)=10MHz, VCC1=2.7 to 5.5V)	41.7ns(f(BCLK)=24MHz, VCC1=4.0 to 5.5V)
	Operating Mode	Single-chip, memory expansion and microprocessor mode	Single-chip
	Address Space	1 Mbyte (Available to 4 Mbytes by memory space expansion function)	1 Mbyte
	Memory Capacity	See <b>Table 1.4 to 1.7 Product List</b>	
Peripheral Function	Port	Input/Output : 87 pins, Input : 1 pin	
	Multifunction Timer	Timer A : 16 bits x 5 channels, Timer B : 16 bits x 6 channels, Three phase motor control circuit	
	Serial Interface	3 channels Clock synchronous, UART, I <sup>2</sup> C bus <sup>(1)</sup> , IEBus <sup>(2)</sup> 2 channels Clock synchronous	
	A/D Converter	10-bit A/D converter: 1 circuit, 26 channels	
	D/A Converter	8 bits x 2 channels	
	DMAC	2 channels	
	CRC Calculation Circuit	CCITT-CRC	
	Watchdog Timer	15 bits x 1 channel (with prescaler)	
	Interrupt	Internal: 29 sources, External: 8 sources, Software: 4 sources, Priority level: 7 levels	
	Clock Generation Circuit	4 circuits Main clock generation circuit (*), Subclock generation circuit (*), On-chip oscillator, PLL synthesizer (*)Equipped with a built-in feedback resistor.	
	Oscillation Stop Detection Function	Stop detection of main clock oscillation, re-oscillation detection function	
	Voltage Detection Circuit	Available (option <sup>(5)</sup> )	Absent
Electric Characteristics	Supply Voltage	VCC1=3.0 to 5.5 V, VCC2=2.7V to VCC1 (f(BCLK)=24MHz) VCC1=2.7 to 5.5 V, VCC2=2.7V to VCC1 (f(BCLK)=10MHz)	VCC1=VCC2=4.0 to 5.5V (f(BCLK)=24MHz)
	Power Consumption	14 mA (VCC1=VCC2=5V, f(BCLK)=24MHz) 8 mA (VCC1=VCC2=3V, f(BCLK)=10MHz) 1.8μA (VCC1=VCC2=3V, f(XCIN)=32kHz, wait mode) 0.7μA (VCC1=VCC2=3V, stop mode)	14 mA (VCC1=VCC2=5V, f(BCLK)=24MHz) 2.0μA (VCC1=VCC2=5V, f(XCIN)=32kHz, wait mode) 0.8μA (VCC1=VCC2=5V, stop mode)
Flash memory version	Program/Erase Supply Voltage	3.3±0.3 V or 5.0±0.5 V	5.0±0.5 V
	Program and Erase Endurance	100 times (all area) or 1,000 times (user ROM area without block A and block 1) / 10,000 times (block A, block 1) <sup>(3)</sup>	
Operating Ambient Temperature		-20 to 85°C, -40 to 85°C <sup>(3)</sup>	T version : -40 to 85°C V version : -40 to 125°C
Package		100-pin plastic mold QFP, LQFP	

## NOTES:

1. I<sup>2</sup>C bus is a registered trademark of Koninklijke Philips Electronics N. V.
2. IEBus is a registered trademark of NEC Electronics Corporation.
3. See **Table 1.8 and 1.9 Product Code** for the program and erase endurance, and operating ambient temperature.  
In addition 1,000 times/10,000 times are under development as of Jul., 2005. Please inquire about a release schedule.
4. Use the M16C/62PT on VCC1=VCC2
5. All options are on request basis.

**Table 1.10 Pin Characteristics for 128-Pin Package (1)**

Pin No.	Control Pin	Port	Interrupt Pin	Timer Pin	UART Pin	Analog Pin	Bus Control Pin
1	VREF						
2	AVCC						
3		P9_7			SIN4	ADTRG	
4		P9_6			SOUT4	ANEX1	
5		P9_5			CLK4	ANEX0	
6		P9_4		TB4IN		DA1	
7		P9_3		TB3IN		DA0	
8		P9_2		TB2IN	SOUT3		
9		P9_1		TB1IN	SIN3		
10		P9_0		TB0IN	CLK3		
11		P14_1					
12		P14_0					
13	BYTE						
14	CNVSS						
15	XCIN	P8_7					
16	XCOUT	P8_6					
17	RESET						
18	XOUT						
19	VSS						
20	XIN						
21	VCC1						
22		P8_5	NMI				
23		P8_4	INT2	ZP			
24		P8_3	INT1				
25		P8_2	INT0				
26		P8_1		TA4IN/U			
27		P8_0		TA4OUT/U			
28		P7_7		TA3IN			
29		P7_6		TA3OUT			
30		P7_5		TA2IN/W			
31		P7_4		TA2OUT/W			
32		P7_3		TA1IN/V	CTS2/RTS2		
33		P7_2		TA1OUT/V	CLK2		
34		P7_1		TA0IN/TB5IN	RXD2/SCL2		
35		P7_0		TA0OUT	TXD2/SDA2		
36		P6_7			TXD1/SDA1		
37	VCC1						
38		P6_6			RXD1/SCL1		
39	VSS						
40		P6_5			CLK1		
41		P6_4			CTS1/RTS1/CTS0/CLKS1		
42		P6_3			TXD0/SDA0		
43		P6_2			RXD0/SCL0		
44		P6_1			CLK0		
45		P6_0			CTS0/RTS0		
46		P13_7					
47		P13_6					
48		P13_5					
49		P13_4					
50		P5_7					RDY/CLKOUT

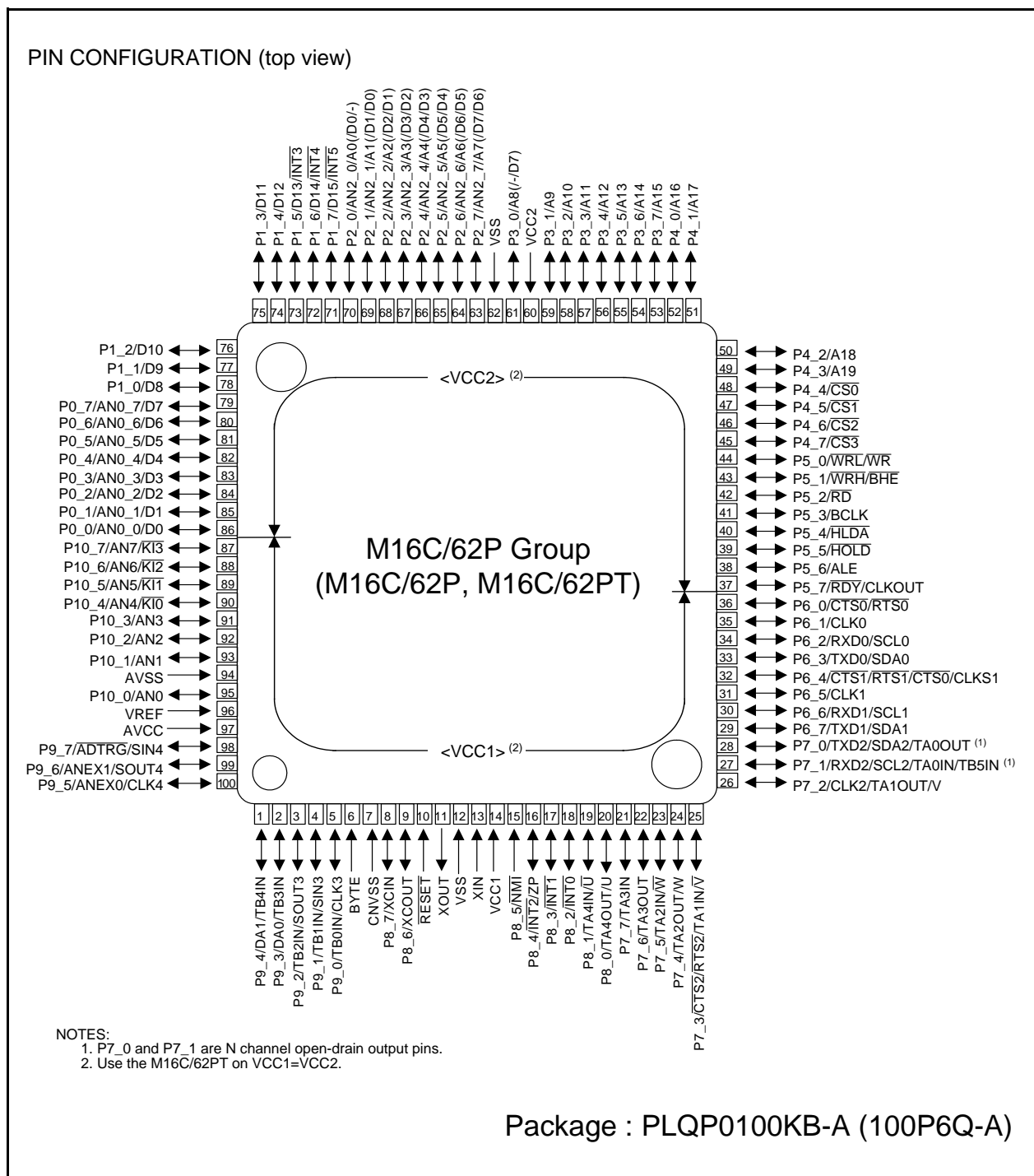


Figure 1.8 Pin Configuration (Top View)

**Table 1.13 Pin Characteristics for 100-Pin Package (1)**

Pin No.		Control Pin	Port	Interrupt Pin	Timer Pin	UART Pin	Analog Pin	Bus Control Pin
FP	GP							
1	99		P9_6			SOUT4	ANEX1	
2	100		P9_5			CLK4	ANEX0	
3	1		P9_4		TB4IN		DA1	
4	2		P9_3		TB3IN		DA0	
5	3		P9_2		TB2IN	SOUT3		
6	4		P9_1		TB1IN	SIN3		
7	5		P9_0		TB0IN	CLK3		
8	6	BYTE						
9	7	CNVSS						
10	8	XCIN	P8_7					
11	9	XCOUT	P8_6					
12	10	RESET						
13	11	XOUT						
14	12	VSS						
15	13	XIN						
16	14	VCC1						
17	15		P8_5	NMI				
18	16		P8_4	INT2	ZP			
19	17		P8_3	INT1				
20	18		P8_2	INT0				
21	19		P8_1		TA4IN/ $\bar{U}$			
22	20		P8_0		TA4OUT/U			
23	21		P7_7		TA3IN			
24	22		P7_6		TA3OUT			
25	23		P7_5		TA2IN/ $\bar{W}$			
26	24		P7_4		TA2OUT/W			
27	25		P7_3		TA1IN/ $\bar{V}$	CTS2/RTS2		
28	26		P7_2		TA1OUT/V	CLK2		
29	27		P7_1		TA0IN/TB5IN	RXD2/SCL2		
30	28		P7_0		TA0OUT	TXD2/SDA2		
31	29		P6_7			TXD1/SDA1		
32	30		P6_6			RXD1/SCL1		
33	31		P6_5			CLK1		
34	32		P6_4			CTS1/RTS1/CTS0/CLKS1		
35	33		P6_3			TXD0/SDA0		
36	34		P6_2			RXD0/SCL0		
37	35		P6_1			CLK0		
38	36		P6_0			CTS0/RTS0		
39	37		P5_7					RDY/CLKOUT
40	38		P5_6					ALE
41	39		P5_5					HOLD
42	40		P5_4					HLAD
43	41		P5_3					BCLK
44	42		P5_2					RD
45	43		P5_1					WRH/BHE
46	44		P5_0					WRL/WR
47	45		P4_7					CS3
48	46		P4_6					CS2
49	47		P4_5					CS1
50	48		P4_4					CS0

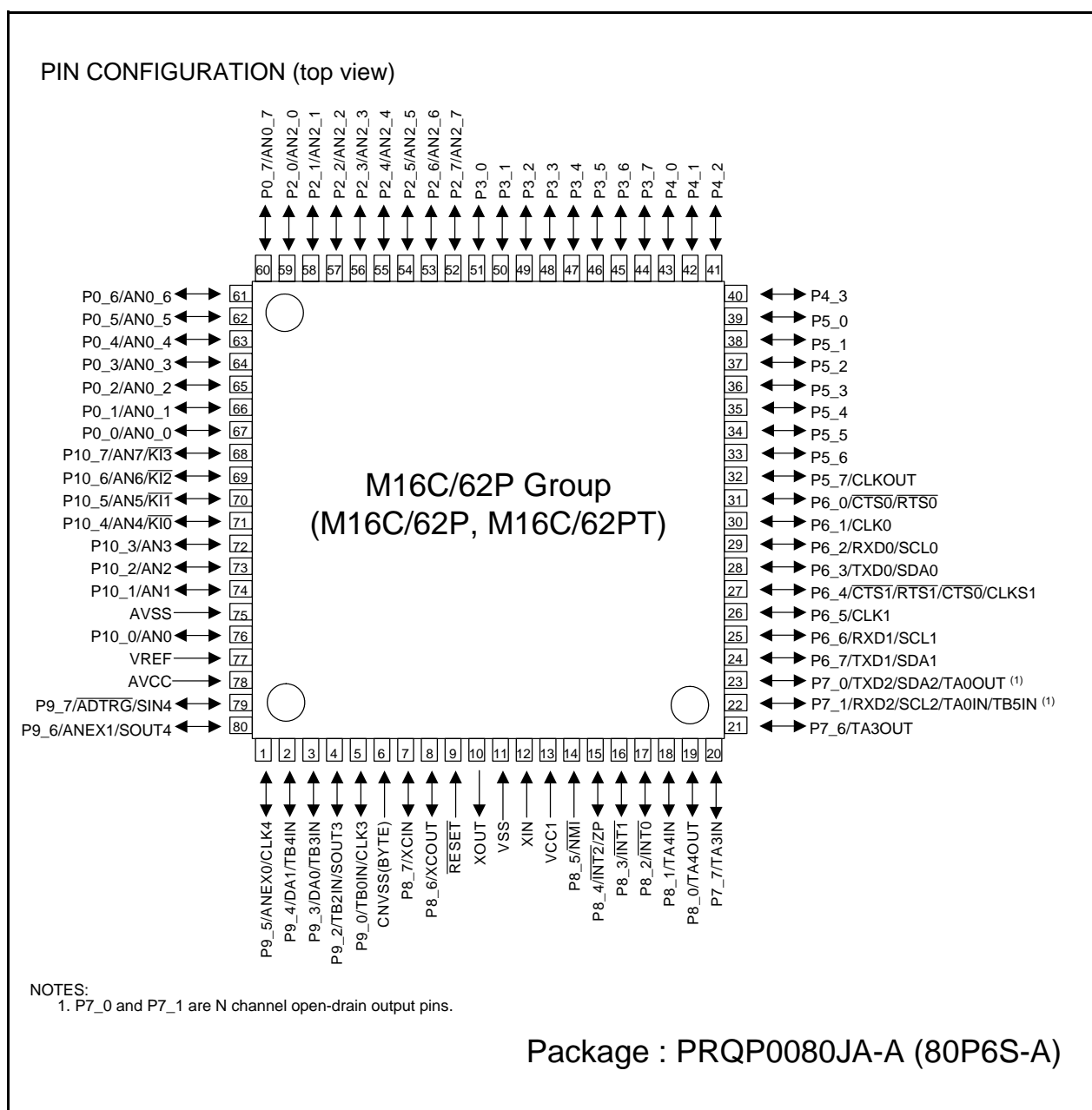


Figure 1.9 Pin Configuration (Top View)

**Table 1.15 Pin Characteristics for 80-Pin Package (1)**

Pin No.	Control Pin	Port	Interrupt Pin	Timer Pin	UART Pin	Analog Pin	Bus Control Pin
1		P9_5			CLK4	ANEX0	
2		P9_4		TB4IN		DA1	
3		P9_3		TB3IN		DA0	
4		P9_2		TB2IN	SOUT3		
5		P9_0		TB0IN	CLK3		
6	CNVSS (BYTE)						
7	XCIN	P8_7					
8	XCOUT	P8_6					
9	RESET						
10	XOUT						
11	VSS						
12	XIN						
13	VCC1						
14		P8_5	NMI				
15		P8_4	INT2	ZP			
16		P8_3	INT1				
17		P8_2	INT0				
18		P8_1		TA4IN			
19		P8_0		TA4OUT			
20		P7_7		TA3IN			
21		P7_6		TA3OUT			
22		P7_1		TA0IN/TB5IN	RXD2/SCL2		
23		P7_0		TA0OUT	TXD2/SDA2		
24		P6_7			TXD1/SDA1		
25		P6_6			RXD1/SCL1		
26		P6_5			CLK1		
27		P6_4			CTS1/RTS1/CTS0/CLKS1		
28		P6_3			TXD0/SDA0		
29		P6_2			RXD0/SCL0		
30		P6_1			CLK0		
31		P6_0			CTS0/RTS0		
32		P5_7					CLKOUT
33		P5_6					
34		P5_5					
35		P5_4					
36		P5_3					
37		P5_2					
38		P5_1					
39		P5_0					
40		P4_3					
41		P4_2					
42		P4_1					
43		P4_0					
44		P3_7					
45		P3_6					
46		P3_5					
47		P3_4					
48		P3_3					
49		P3_2					
50		P3_1					

**Table 1.16 Pin Characteristics for 80-Pin Package (2)**

Pin No.	Control Pin	Port	Interrupt Pin	Timer Pin	UART Pin	Analog Pin	Bus Control Pin
51		P3_0					
52		P2_7				AN2_7	
53		P2_6				AN2_6	
54		P2_5				AN2_5	
55		P2_4				AN2_4	
56		P2_3				AN2_3	
57		P2_2				AN2_2	
58		P2_1				AN2_1	
59		P2_0				AN2_0	
60		P0_7				AN0_7	
61		P0_6				AN0_6	
62		P0_5				AN0_5	
63		P0_4				AN0_4	
64		P0_3				AN0_3	
65		P0_2				AN0_2	
66		P0_1				AN0_1	
67		P0_0				AN0_0	
68		P10_7	$\overline{\text{KI3}}$			AN7	
69		P10_6	$\overline{\text{KI2}}$			AN6	
70		P10_5	$\overline{\text{KI1}}$			AN5	
71		P10_4	$\overline{\text{KI0}}$			AN4	
72		P10_3				AN3	
73		P10_2				AN2	
74		P10_1				AN1	
75	AVSS						
76		P10_0				AN0	
77	VREF						
78	AVCC						
79		P9_7			SIN4	$\overline{\text{ADTRG}}$	
80		P9_6			SOUT4	ANEX1	



**Table 1.18 Pin Description (100-pin and 128-pin Version) (2)**

Signal Name	Pin Name	I/O Type	Power Supply <sup>(1)</sup>	Description
Main clock input	XIN	I	VCC1	I/O pins for the main clock generation circuit. Connect a ceramic resonator or crystal oscillator between XIN and XOUT <sup>(3)</sup> . To use the external clock, input the clock from XIN and leave XOUT open.
Main clock output	XOUT	O	VCC1	
Sub clock input	XCIN	I	VCC1	I/O pins for a sub clock oscillation circuit. Connect a crystal oscillator between XCIN and XCOUT <sup>(3)</sup> . To use the external clock, input the clock from XCIN and leave XCOUT open.
Sub clock output	XCOUT	O	VCC1	
BCLK output <sup>(2)</sup>	BCLK	O	VCC2	Outputs the BCLK signal.
Clock output	CLKOUT	O	VCC2	The clock of the same cycle as fC, f8, or f32 is outputted.
INT interrupt input	INT0 to INT2	I	VCC1	Input pins for the INT interrupt.
	INT3 to INT5	I	VCC2	
NMI interrupt input	NMI	I	VCC1	Input pin for the NMI interrupt. Pin states can be read by the P8_5 bit in the P8 register.
Key input interrupt input	KI0 to KI3	I	VCC1	Input pins for the key input interrupt.
Timer A	TA0OUT to TA4OUT	I/O	VCC1	These are timer A0 to timer A4 I/O pins. (however, output of TA0OUT for the N-channel open drain output.)
	TA0IN to TA4IN	I	VCC1	These are timer A0 to timer A4 input pins.
	ZP	I	VCC1	Input pin for the Z-phase.
Timer B	TB0IN to TB5IN	I	VCC1	These are timer B0 to timer B5 input pins.
Three-phase motor control output	U, $\bar{U}$ , V, $\bar{V}$ , W, $\bar{W}$	O	VCC1	These are Three-phase motor control output pins.
Serial interface	$\overline{\text{CTS0}}$ to $\overline{\text{CTS2}}$	I	VCC1	These are send control input pins.
	$\overline{\text{RTS0}}$ to $\overline{\text{RTS2}}$	O	VCC1	These are receive control output pins.
	CLK0 to CLK4	I/O	VCC1	These are transfer clock I/O pins.
	RXD0 to RXD2	I	VCC1	These are serial data input pins.
	SIN3, SIN4	I	VCC1	These are serial data input pins.
	TXD0 to TXD2	O	VCC1	These are serial data output pins. (however, output of TXD2 for the N-channel open drain output.)
	SOUT3, SOUT4	O	VCC1	These are serial data output pins.
	CLKS1	O	VCC1	This is output pin for transfer clock output from multiple pins function.
I <sup>2</sup> C mode	SDA0 to SDA2	I/O	VCC1	These are serial data I/O pins. (however, output of SDA2 for the N-channel open drain output.)
	SCL0 to SCL2	I/O	VCC1	These are transfer clock I/O pins. (however, output of SCL2 for the N-channel open drain output.)

I : Input O : Output I/O : Input and output

## NOTES:

1. When use VCC1 > VCC2, contacts due to some points or restrictions to be checked.
2. This pin function in M16C/62PT cannot be used.
3. Ask the oscillator maker the oscillation characteristic.

**Table 1.19 Pin Description (100-pin and 128-pin Version) (3)**

Signal Name	Pin Name	I/O Type	Power Supply <sup>(1)</sup>	Description
Reference voltage input	VREF	I	VCC1	Applies the reference voltage for the A/D converter and D/A converter.
A/D converter	AN0 to AN7, AN0_0 to AN0_7, AN2_0 to AN2_7	I	VCC1	Analog input pins for the A/D converter.
	ADTRG	I	VCC1	This is an A/D trigger input pin.
	ANEX0	I/O	VCC1	This is the extended analog input pin for the A/D converter, and is the output in external op-amp connection mode.
	ANEX1	I	VCC1	This is the extended analog input pin for the A/D converter.
D/A converter	DA0, DA1	O	VCC1	This is the output pin for the D/A converter.
I/O port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7 (2), P13_0 to P13_7 (2)	I/O	VCC2	8-bit I/O ports in CMOS, having a direction register to select an input or output. Each pin is set as an input port or output port. An input port can be set for a pull-up or for no pull-up in 4-bit unit by program.
	P6_0 to P6_7, P7_0 to P7_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7 (2)	I/O	VCC1	8-bit I/O ports having equivalent functions to P0. (however, output of P7_0 and P7_1 for the N-channel open drain output.)
	P8_0 to P8_4, P8_6, P8_7, P14_0, P14_1(2)	I/O	VCC1	I/O ports having equivalent functions to P0.
Input port	P8_5	I	VCC1	Input pin for the $\overline{\text{NMI}}$ interrupt. Pin states can be read by the P8_5 bit in the P8 register.

I : Input O : Output I/O : Input and output

## NOTES:

1. When use VCC1 > VCC2, contacts due to some points or restrictions to be checked.
2. Ports P11 to P14 in M16C/62P (100-pin version) and M16C/62PT (100-pin version) cannot be used.

### **2.8.8 Stack Pointer Select Flag (U Flag)**

ISP is selected when the U flag is “0”; USP is selected when the U flag is “1”.

The U flag is cleared to “0” when a hardware interrupt request is accepted or an INT instruction for software interrupt Nos. 0 to 31 is executed.

### **2.8.9 Processor Interrupt Priority Level (IPL)**

IPL is configured with three bits, for specification of up to eight processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has priority greater than IPL, the interrupt is enabled.

### **2.8.10 Reserved Area**

When write to this bit, write “0”. When read, its content is indeterminate.

### 3. Memory

Figure 3.1 is a Memory Map of the M16C/62P group. The address space extends the 1M bytes from address 00000h to FFFFFh.

The internal ROM is allocated in a lower address direction beginning with address FFFFFh. For example, a 64-Kbyte internal ROM is allocated to the addresses from F0000h to FFFFFh.

As for the flash memory version, 4-Kbyte space (block A) exists in 0F000h to 0FFFFh. 4-Kbyte space is mainly for storing data. In addition to storing data, 4-Kbyte space also can store programs.

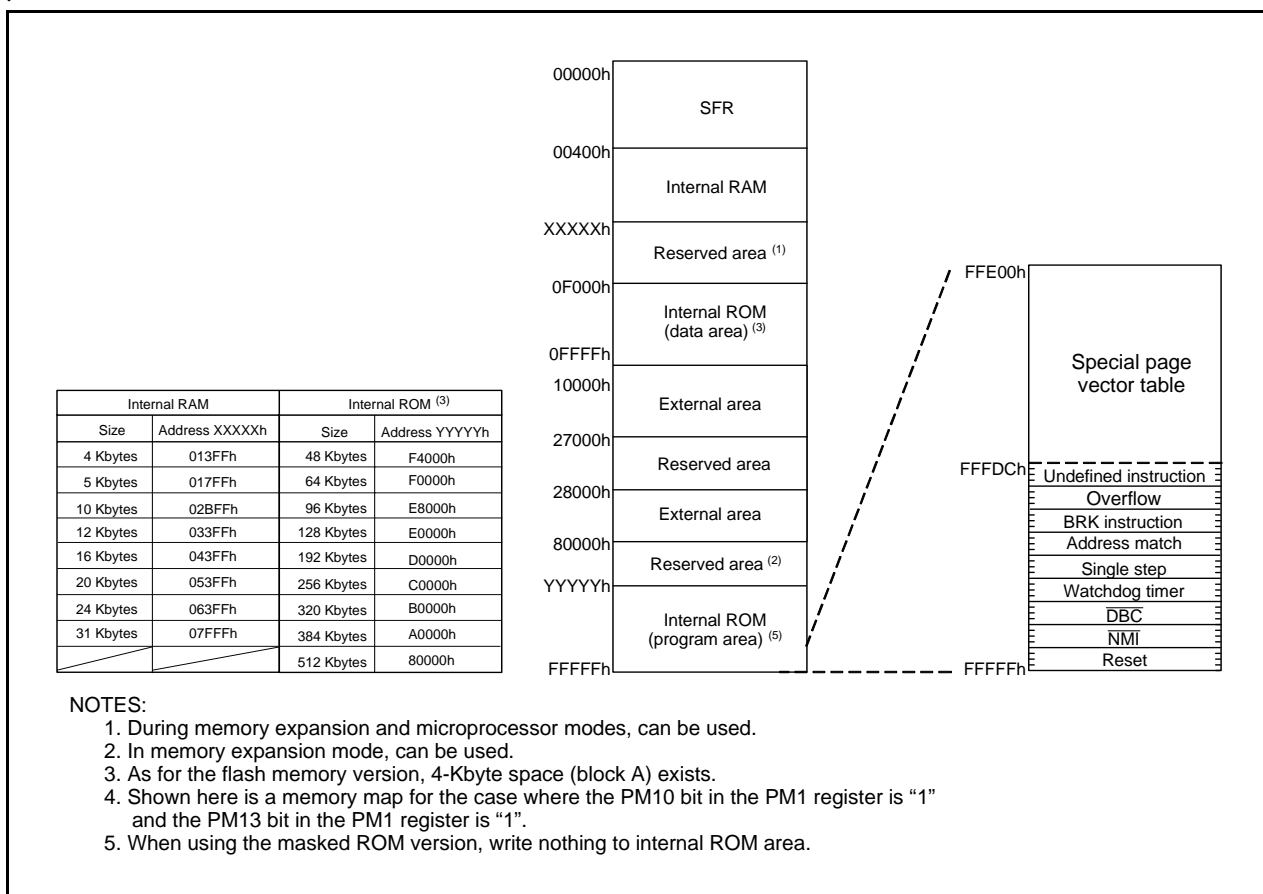
The fixed interrupt vector table is allocated to the addresses from FFFDCh to FFFFFh. Therefore, store the start address of each interrupt routine here.

The internal RAM is allocated in an upper address direction beginning with address 00400h. For example, a 10-Kbyte internal RAM is allocated to the addresses from 00400h to 02BFFh. In addition to storing data, the internal RAM also stores the stack used when calling subroutines and when interrupts are generated.

The SRF is allocated to the addresses from 00000h to 003FFh. Peripheral function control registers are located here. Of the SFR, any area which has no functions allocated is reserved for future use and cannot be used by users.

The special page vector table is allocated to the addresses from FFE00h to FFFDBh. This vector is used by the JMPS or JSRS instruction. For details, refer to the **M16C/60 and M16C/20 Series Software Manual**.

In memory expansion and microprocessor modes, some areas are reserved for future use and cannot be used by users. Use M16C/62P (80-pin version) and M16C/62PT in single-chip mode. The memory expansion and microprocessor modes cannot be used



**Figure 3.1 Memory Map**

**Table 5.9 Low Voltage Detection Circuit Electrical Characteristics**

Symbol	Parameter	Measuring Condition	Standard			Unit
			Min.	Typ.	Max.	
V <sub>det4</sub>	Low Voltage Detection Voltage <sup>(1)</sup>	V <sub>CC1</sub> =0.8V to 5.5V	3.3	3.8	4.4	V
V <sub>det3</sub>	Reset Level Detection Voltage <sup>(1, 2)</sup>		2.2	2.8	3.6	V
V <sub>det4</sub> -V <sub>det3</sub>	Electric potential difference of Low Voltage Detection and Reset Level Detection		0.3			V
V <sub>det3s</sub>	Low Voltage Reset Retention Voltage				0.8	V
V <sub>det3r</sub>	Low Voltage Reset Release Voltage <sup>(3)</sup>		2.2	2.9	4.0	V

## NOTES:

1. V<sub>det4</sub> > V<sub>det3</sub>.
2. Where reset level detection voltage is less than 2.7 V, if the supply power voltage is greater than the reset level detection voltage, the microcomputer operates with f(BCLK) ≤ 10MHz.
3. V<sub>det3r</sub> > V<sub>det3</sub> is not guaranteed.
4. The voltage detection circuit is designed to use when V<sub>CC1</sub> is set to 5V.

**Table 5.10 Power Supply Circuit Timing Characteristics**

Symbol	Parameter	Measuring Condition	Standard			Unit
			Min.	Typ.	Max.	
t <sub>d</sub> (P-R)	Time for Internal Power Supply Stabilization During Powering-On	V <sub>CC1</sub> =2.7V to 5.5V			2	ms
t <sub>d</sub> (R-S)	STOP Release Time				150	μs
t <sub>d</sub> (W-S)	Low Power Dissipation Mode Wait Mode Release Time				150	μs
t <sub>d</sub> (S-R)	Brown-out Detection Reset (Hardware Reset 2) Release Wait Time	V <sub>CC1</sub> =V <sub>det3r</sub> to 5.5V		6 <sup>(1)</sup>	20	ms
t <sub>d</sub> (E-A)	Low Voltage Detection Circuit Operation Start Time	V <sub>CC1</sub> =2.7V to 5.5V			20	μs

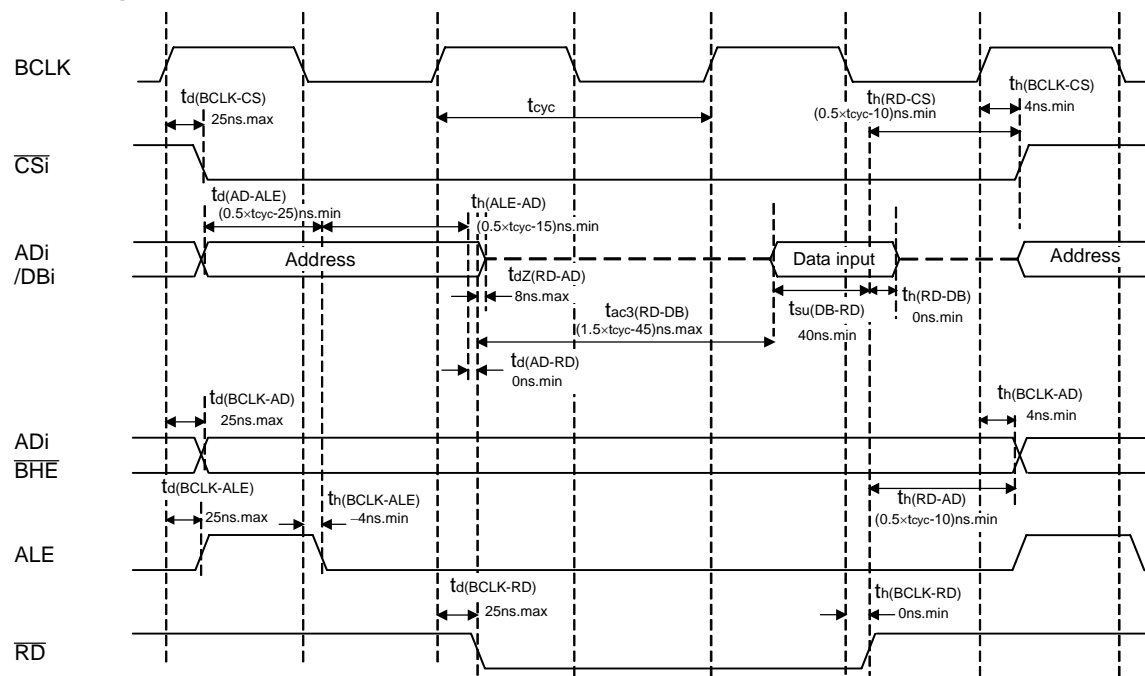
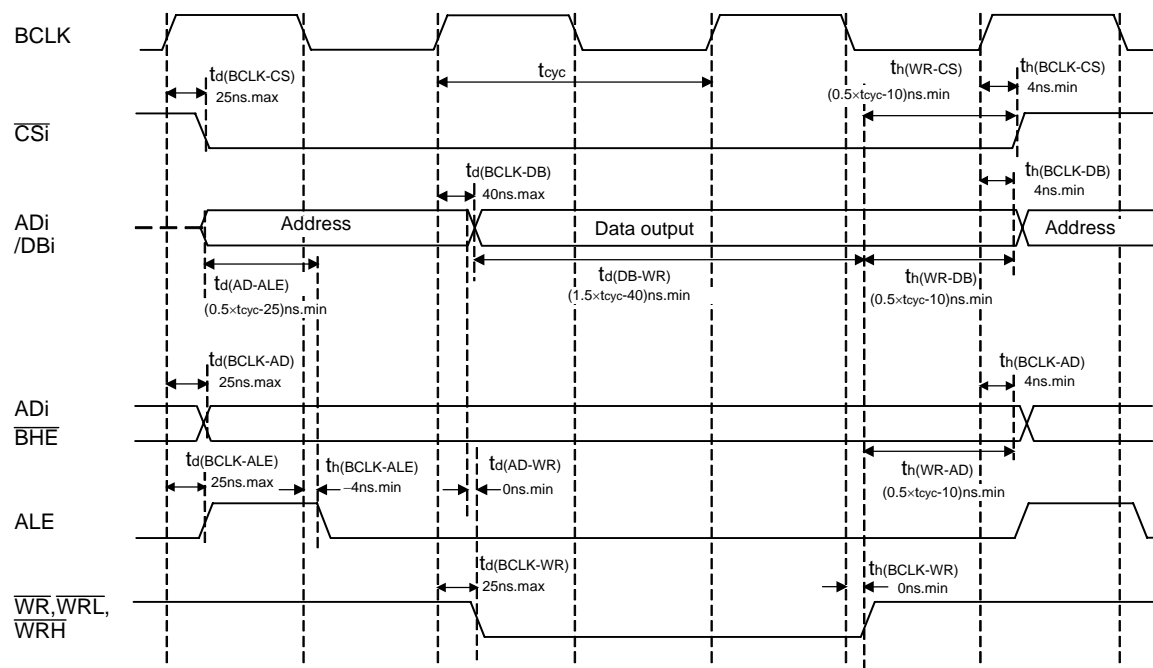
## NOTES:

1. When V<sub>CC1</sub> = 5V.

VCC1=VCC2=5V

**Memory Expansion Mode, Microprocessor Mode**

(For 1- or 2-wait setting, external area access and multiplex bus selection)

**Read timing****Write timing****Measuring conditions**

- VCC1=VCC2=5V
- Input timing voltage :  $V_{IL}=0.8\text{V}$ ,  $V_{IH}=2.0\text{V}$
- Output timing voltage :  $V_{OL}=0.4\text{V}$ ,  $V_{OH}=2.4\text{V}$

**Figure 5.10 Timing Diagram (8)**

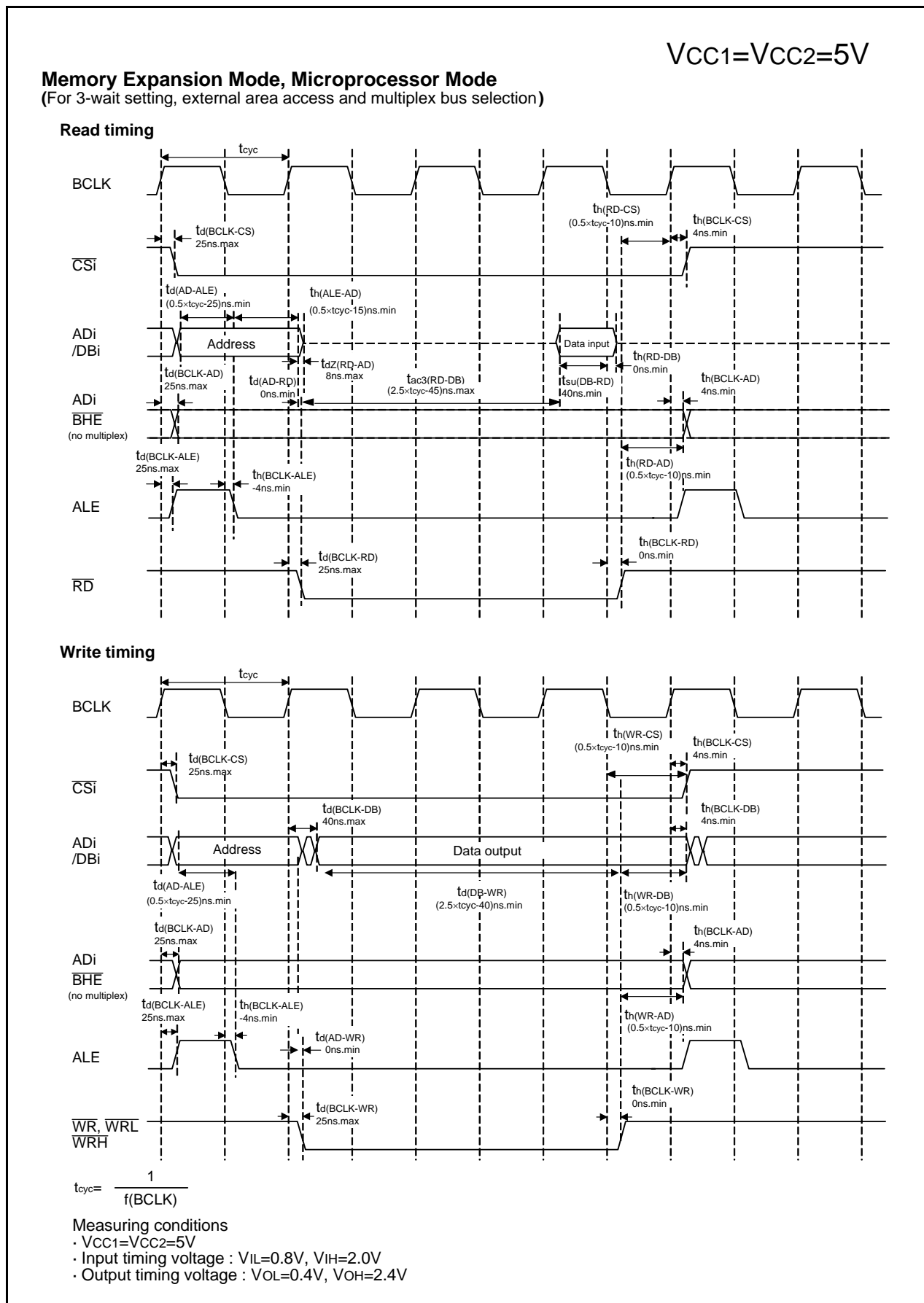


Figure 5.11 Timing Diagram (9)

$$V_{CC1}=V_{CC2}=3V$$

**Switching Characteristics**

( $V_{CC1} = V_{CC2} = 5V$ ,  $V_{SS} = 0V$ , at  $T_{opr} = -20$  to  $85^{\circ}C$  /  $-40$  to  $85^{\circ}C$  unless otherwise specified)

**Table 5.47 Memory Expansion and Microprocessor Modes (for 1- to 3-wait setting and external area access)**

Symbol	Parameter		Standard		Unit
			Min.	Max.	
$t_d(BCLK-AD)$	Address Output Delay Time	See Figure 5.12		30	ns
$t_h(BCLK-AD)$	Address Output Hold Time (in relation to BCLK)		4		ns
$t_h(RD-AD)$	Address Output Hold Time (in relation to RD)		0		ns
$t_h(WR-AD)$	Address Output Hold Time (in relation to WR)		(NOTE 2)		ns
$t_d(BCLK-CS)$	Chip Select Output Delay Time			30	ns
$t_h(BCLK-CS)$	Chip Select Output Hold Time (in relation to BCLK)		4		ns
$t_d(BCLK-ALE)$	ALE Signal Output Delay Time			25	ns
$t_h(BCLK-ALE)$	ALE Signal Output Hold Time		-4		ns
$t_d(BCLK-RD)$	RD Signal Output Delay Time			30	ns
$t_h(BCLK-RD)$	RD Signal Output Hold Time		0		ns
$t_d(BCLK-WR)$	WR Signal Output Delay Time			30	ns
$t_h(BCLK-WR)$	WR Signal Output Hold Time		0		ns
$t_d(BCLK-DB)$	Data Output Delay Time (in relation to BCLK)			40	ns
$t_h(BCLK-DB)$	Data Output Hold Time (in relation to BCLK) <sup>(3)</sup>		4		ns
$t_d(DB-WR)$	Data Output Delay Time (in relation to WR)		(NOTE 1)		ns
$t_h(WR-DB)$	Data Output Hold Time (in relation to WR) <sup>(3)</sup>		(NOTE 2)		ns
$t_d(BCLK-HLDA)$	HLDA Output Delay Time			40	ns

**NOTES:**

1. Calculated according to the BCLK frequency as follows:

$$\frac{(n-0.5) \times 10^9}{f(BCLK)} - 40[ns]$$

n is "1" for 1-wait setting, "2" for 2-wait setting and "3" for 3-wait setting.  
(BCLK) is 12.5MHz or less.

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 10[ns]$$

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.

Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.

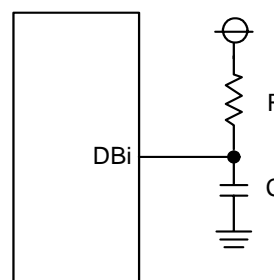
Hold time of data bus is expressed in

$$t = -CR \times \ln(1 - V_{OL} / V_{CC2})$$

by a circuit of the right figure.

For example, when  $V_{OL} = 0.2V_{CC2}$ ,  $C = 30pF$ ,  $R = 1k\Omega$ , hold time of output "L" level is

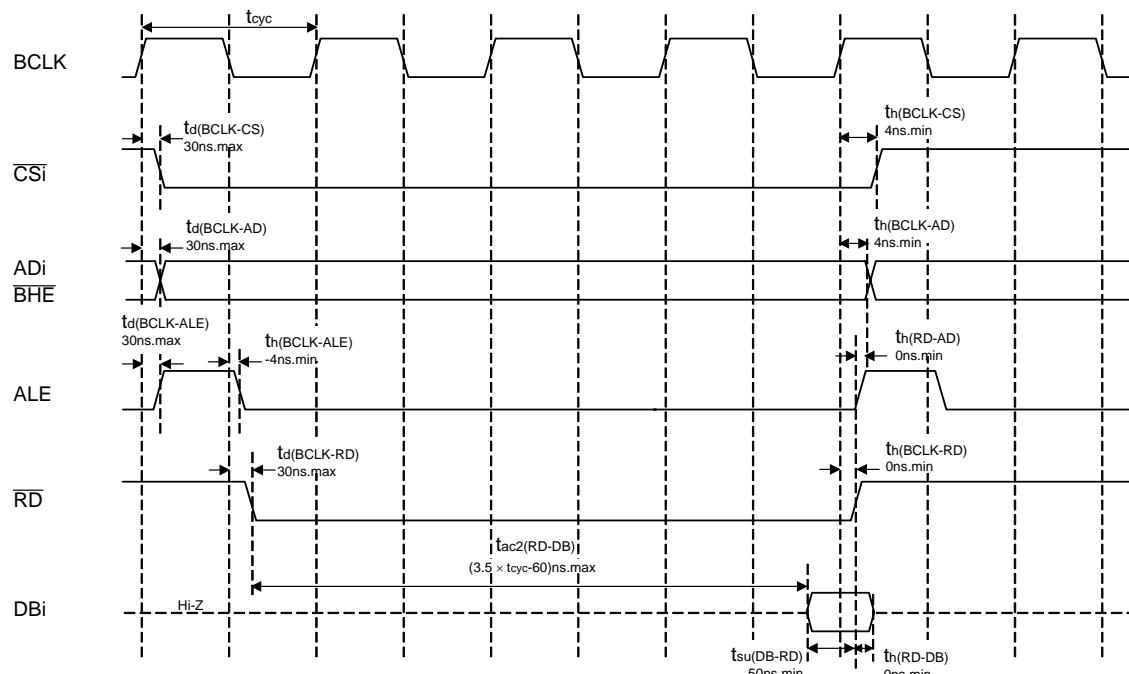
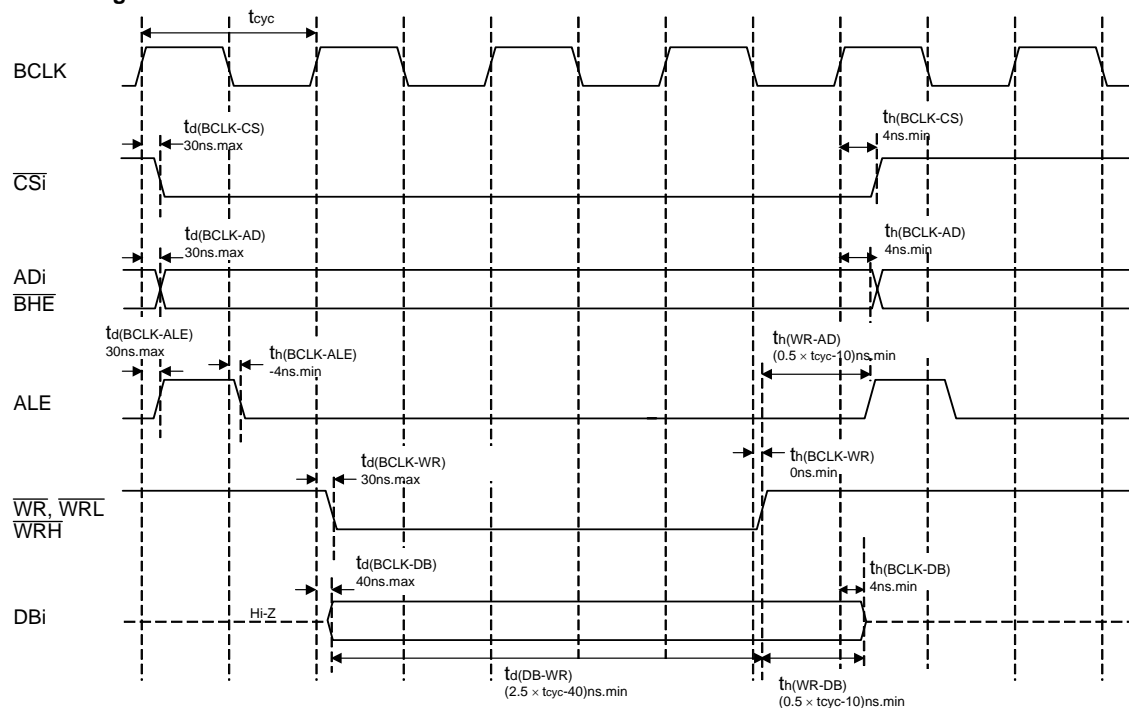
$$t = -30pF \times 1k\Omega \times \ln(1 - 0.2V_{CC2} / V_{CC2}) \\ = 6.7ns.$$





**Memory Expansion Mode, Microprocessor Mode**  
 (for 3-wait setting and external area access)

$$V_{CC1} = V_{CC2} = 3V$$

**Read timing**

**Write timing**


$$t_{cyc} = \frac{1}{f(BCLK)}$$

**Measuring conditions**

- $V_{CC1}=V_{CC2}=3V$
- Input timing voltage :  $V_{IL}=0.6V$ ,  $V_{IH}=2.4V$
- Output timing voltage :  $V_{OL}=1.5V$ ,  $V_{OH}=1.5V$

**Figure 5.19 Timing Diagram (7)**

**Table 5.50 Recommended Operating Conditions (1) (1)**

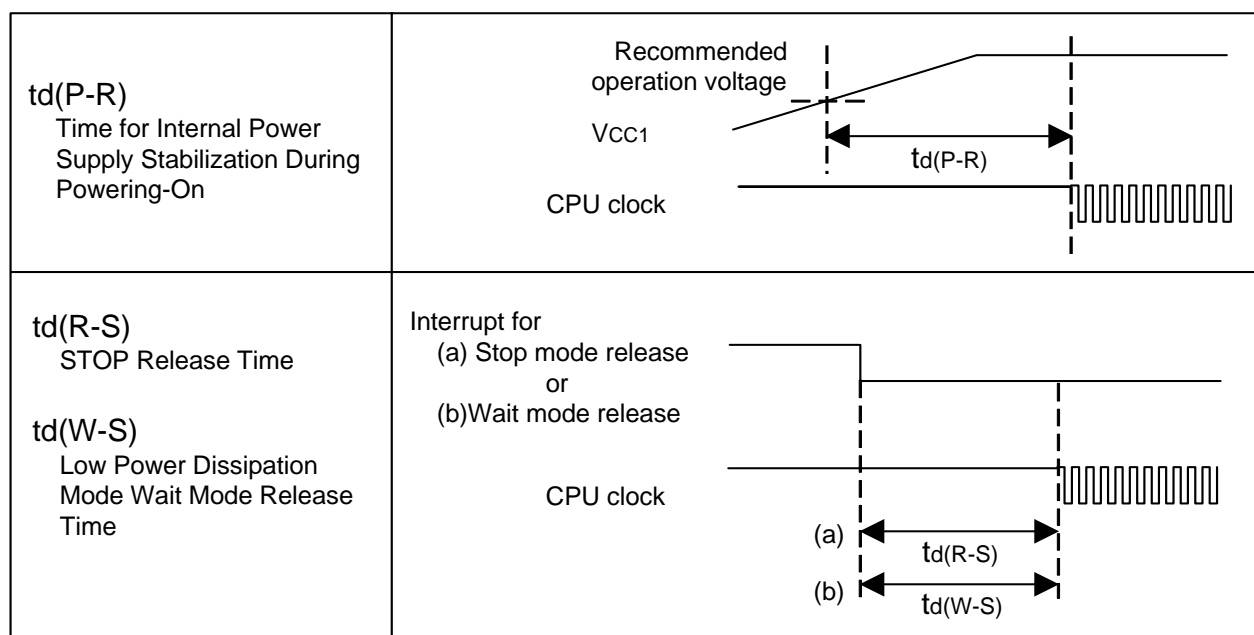
Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
V <sub>CC1</sub> , V <sub>CC2</sub>	Supply Voltage (V <sub>CC1</sub> = V <sub>CC2</sub> )		4.0	5.0	5.5	V
AV <sub>CC</sub>	Analog Supply Voltage			V <sub>CC1</sub>		V
V <sub>SS</sub>	Supply Voltage			0		V
AV <sub>SS</sub>	Analog Supply Voltage			0		V
V <sub>IH</sub>	HIGH Input Voltage (4)	P3_1 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7	0.8V <sub>CC2</sub>		V <sub>CC2</sub>	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (during single-chip mode)	0.8V <sub>CC2</sub>		V <sub>CC2</sub>	V
		P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1, XIN, RESET, CNVSS, BYTE	0.8V <sub>CC1</sub>		V <sub>CC1</sub>	V
		P7_0, P7_1	0.8V <sub>CC1</sub>		6.5	V
V <sub>IL</sub>	LOW Input Voltage (4)	P3_1 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7	0		0.2V <sub>CC2</sub>	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (during single-chip mode)	0		0.2V <sub>CC2</sub>	V
		P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1, XIN, RESET, CNVSS, BYTE	0		0.2V <sub>CC</sub>	V
I <sub>OH(peak)</sub>	HIGH Peak Output Current (4)	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1			−10.0	mA
I <sub>OH(avg)</sub>	HIGH Average Output Current (4)	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1			−5.0	mA
I <sub>OL(peak)</sub>	LOW Peak Output Current (4)	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1			10.0	mA
I <sub>OL(avg)</sub>	LOW Average Output Current (4)	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1			5.0	mA
f(XIN)	Main Clock Input Oscillation Frequency	V <sub>CC1</sub> =4.0V to 5.5V	0		16	MHz
f(XCIN)	Sub-Clock Oscillation Frequency			32.768	50	kHz
f(Ring)	On-chip Oscillation Frequency		0.5	1	2	MHz
f(PLL)	PLL Clock Oscillation Frequency	V <sub>CC1</sub> =4.0V to 5.5V	10		24	MHz
f(BCLK)	CPU Operation Clock		0		24	MHz
t <sub>su(PLL)</sub>	PLL Frequency Synthesizer Stabilization Wait Time	V <sub>CC1</sub> =5.5V			20	ms

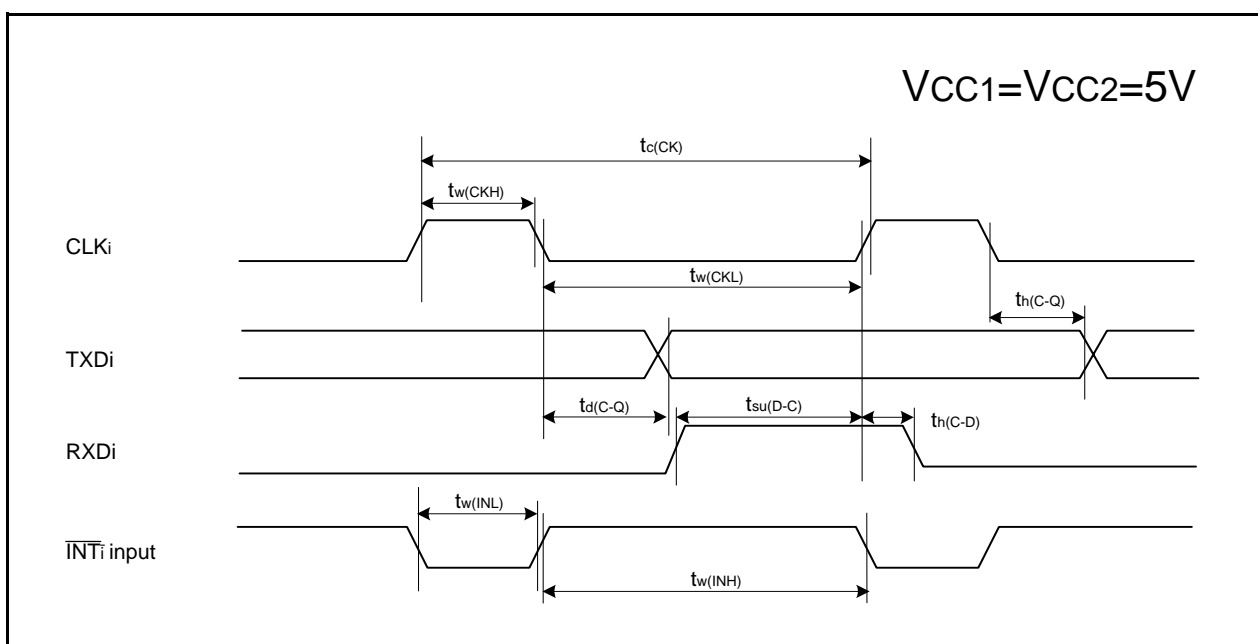
**NOTES:**

1. Referenced to V<sub>CC1</sub> = V<sub>CC2</sub> = 4.7 to 5.5V at T<sub>opr</sub> = −40 to 85°C / −40 to 125°C unless otherwise specified.  
T version = −40 to 85 °C, V version = −40 to 125 °C.
2. The Average Output Current is the mean value within 100ms.
3. The total I<sub>OL(peak)</sub> for ports P0, P1, P2, P8\_6, P8\_7, P9, P10 P1, P14\_0 and P14\_1 must be 80mA max. The total I<sub>OL(peak)</sub> for ports P3, P4, P5, P6, P7, P8\_0 to P8\_4, P12, and P13 must be 80mA max. The total I<sub>OH(peak)</sub> for ports P0, P1, and P2 must be −40mA max. The total I<sub>OH(peak)</sub> for ports P3, P4, P5, P12, and P13 must be −40mA max. The total I<sub>OH(peak)</sub> for ports P6, P7, and P8\_0 to P8\_4 must be −40mA max. The total I<sub>OH(peak)</sub> for ports P8\_6, P8\_7, P9, P10, P11, P14\_0, and P14\_1 must be −40mA max.  
As for 80-pin version, the total I<sub>OL(peak)</sub> for all ports and I<sub>OH(peak)</sub> must be 80mA. max. due to one V<sub>CC</sub> and one V<sub>SS</sub>.
4. There is no external connections for port P1\_0 to P1\_7, P4\_4 to P4\_7, P7\_2 to P7\_5 and P9\_1 in 80-pin version.

**Table 5.56 Power Supply Circuit Timing Characteristics**

Symbol	Parameter	Measuring Condition	Standard			Unit
			Min.	Typ.	Max.	
$t_{d(P-R)}$	Time for Internal Power Supply Stabilization During Powering-On	$V_{CC1}=4.0V$ to $5.5V$			2	ms
$t_{d(R-S)}$	STOP Release Time				150	$\mu s$
$t_{d(W-S)}$	Low Power Dissipation Mode Wait Mode Release Time				150	$\mu s$

**Figure 5.22 Power Supply Circuit Timing Diagram**

**Figure 5.25** Timing Diagram (2)

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